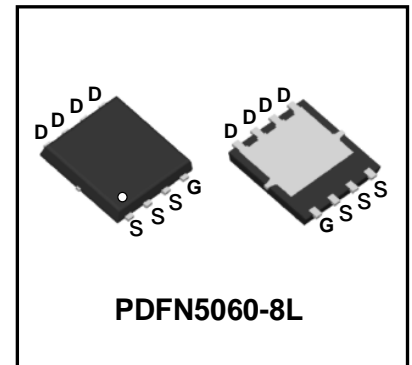


## 100V N-Channel Enhancement Mode Power MOSFET

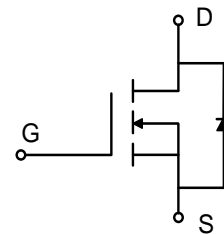
### Description

WMB085N10LG2 uses Wayon's 2<sup>nd</sup> generation POWER TRENCH MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications



### Features

- $V_{DS} = 100\text{ V}$ ,  $I_D = 62\text{ A}$  (Silicon Limited)  
 $R_{DS(on)} < 8.5\text{ m}\Omega @ V_{GS} = 10\text{ V}$   
 $R_{DS(on)} < 10.5\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- Green Device Available
- Low Gate Charge
- 100% EAS Guaranteed
- Low  $R_{DS(ON)}$



### Applications

- Power Management Switches
- Synchronous Rectification for AC/DC Quick Charger

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current@10V <sup>1</sup>	$I_D$	$T_C = 25^\circ\text{C}$	62
		$T_C = 70^\circ\text{C}$	48
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	290	A
Single Pulse Avalanche Energy <sup>3</sup>	<b>EAS</b>	80	mJ
Avalanche Current	$I_{AS}$	40	A
Total Power Dissipation <sup>4</sup>	$T_C = 25^\circ\text{C}$	$P_D$	81
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	55	$^\circ\text{C/W}$
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	1.2	$^\circ\text{C/W}$

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V	
Gate-body Leakage Current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80V, V_{GS} = 0V$	$T_J = 25^\circ\text{C}$	-	-	1	$\mu A$
			$T_J = 55^\circ\text{C}$	-	-	5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	-	2.3	V	
Drain-Source On-Resistance <sup>2</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 13.5A$	-	6.5	8.5	m $\Omega$	
		$V_{GS} = 4.5V, I_D = 11.5A$	-	7.8	10.5		
Forward Transconductance	$g_{fs}$	$V_{DS} = 5V, I_D = 20A$	-	85	-	S	
<b>Dynamic Characteristics</b>							
Input Capacitance	$C_{iss}$	$V_{DS} = 50V, V_{GS} = 0V, f = 1MHz$	-	2858	-	$\mu F$	
Output Capacitance	$C_{oss}$		-	450	-		
Reverse Transfer Capacitance	$C_{rss}$		-	13.5	-		
<b>Switching Characteristics</b>							
Gate Resistance	$R_g$	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	-	3.0	-	$\Omega$	
Total Gate Charge	$Q_g$	$V_{GS} = 4.5V, V_{DS} = 50V, I_D=13.5A$  $V_{GS} = 10V, V_{DS} = 50V, I_D=13.5A$	-	21.2	-	nC	
Total Gate Charge	$Q_g$		-	47	-		
Gate-Source Charge	$Q_{gs}$		-	9.5	-		
Gate-Drain Charge	$Q_{gd}$		-	6.8	-		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 50V, R_G = 3\Omega, I_D = 13.5A$	-	19	-	nS	
Rise Time	$t_r$		-	47	-		
Turn-Off Delay Time	$t_{d(off)}$		-	121	-		
Fall Time	$t_f$		-	76	-		
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = 1A, V_{GS} = 0V$	-	-	1.1	V	
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	62	A	
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 13.5A, di/dt = 500A/\mu s$	-	51	-	nS	
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	120	-	nC	

## Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=40A$
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

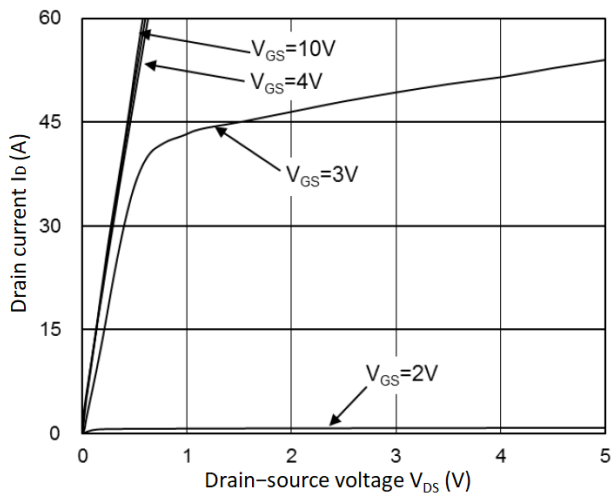


Figure 1. Output Characteristics

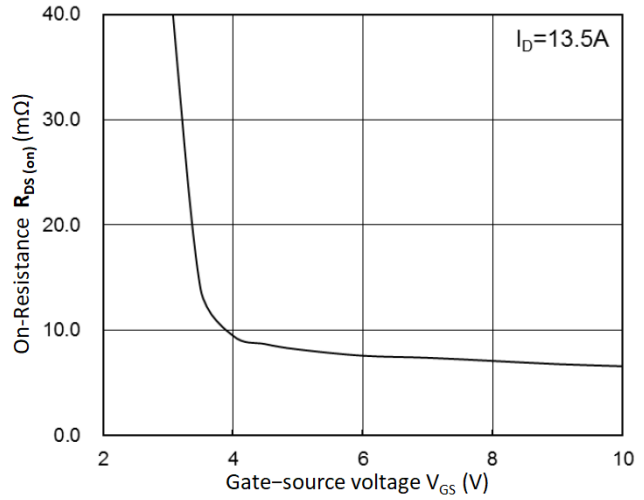


Figure 2.  $R_{DS(on)}$  vs.  $V_{GS}$

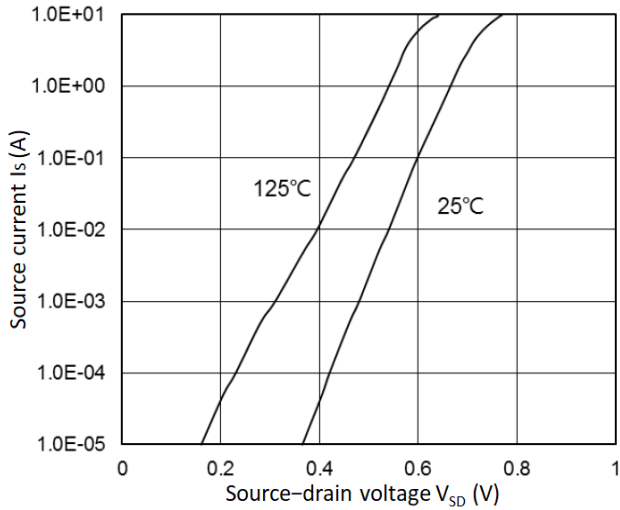


Figure 3. Forward Characteristics of Reverse

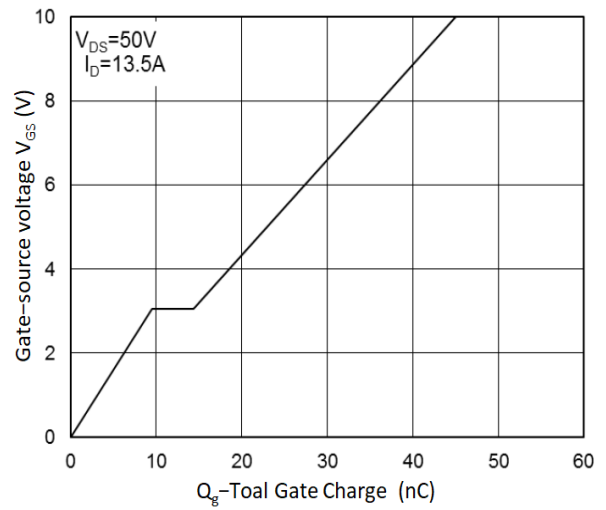


Figure 4. Gate Charge Characteristics

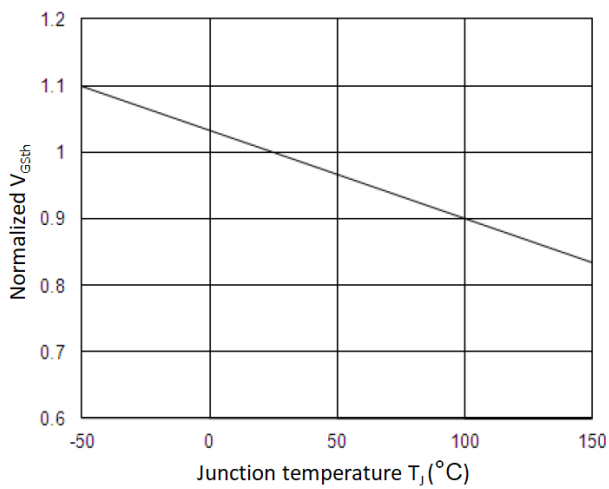


Figure 5. Normalized  $V_{GSth}$  vs.  $T_J$

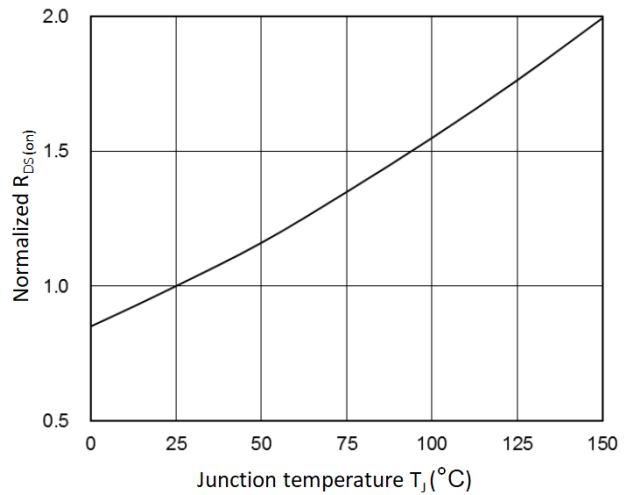


Figure 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

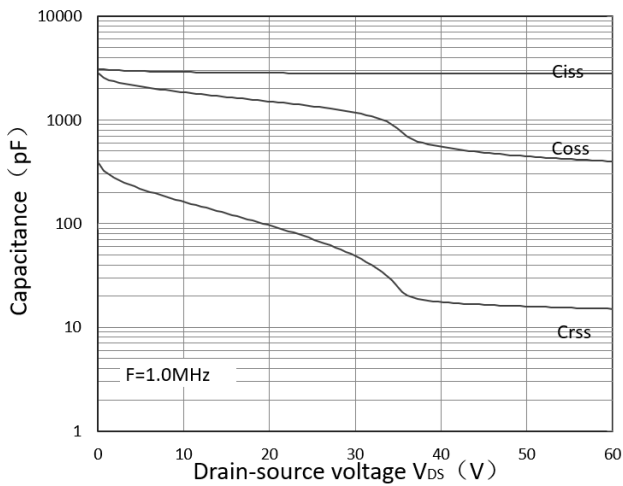


Figure 7. Capacitance Characteristics

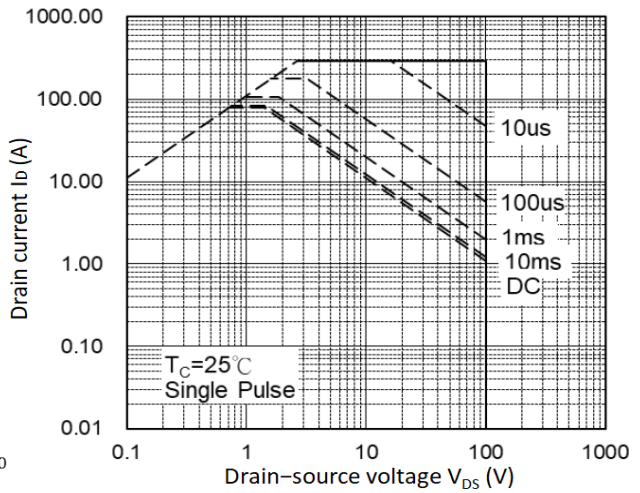


Figure 8. Safe Operating Area

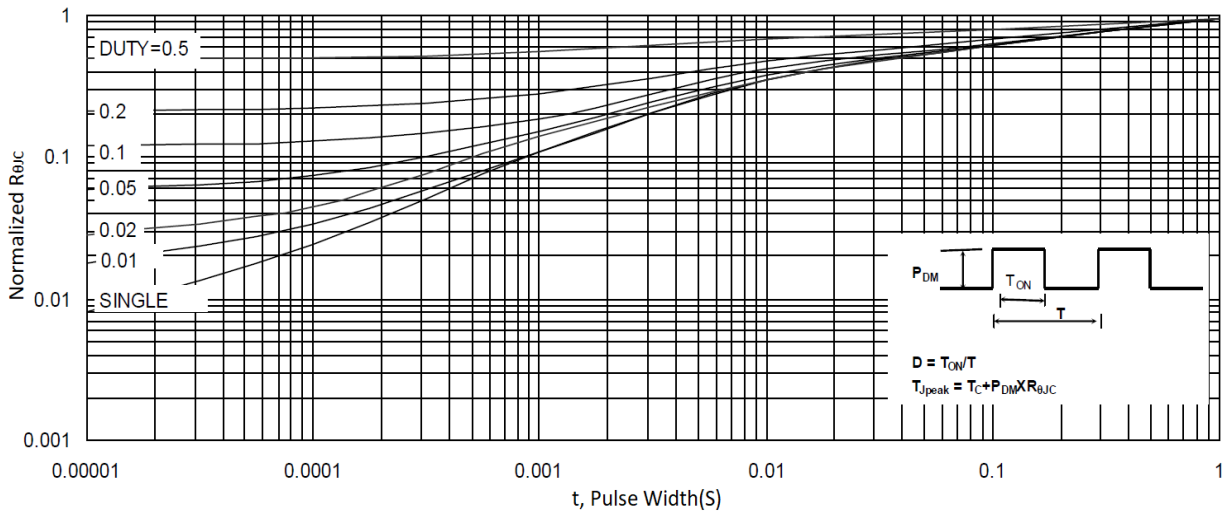


Figure 9. Normalized Maximum Transient Thermal Impedance

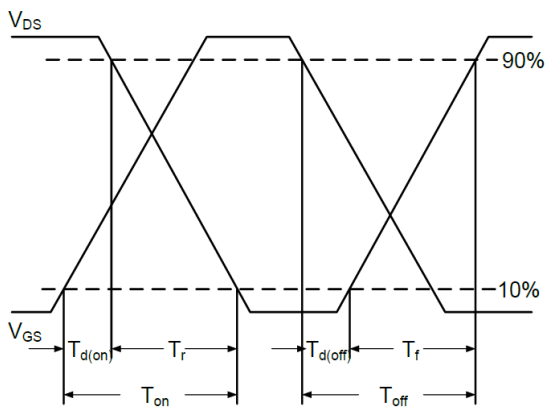


Figure 10. Switching Time Waveform

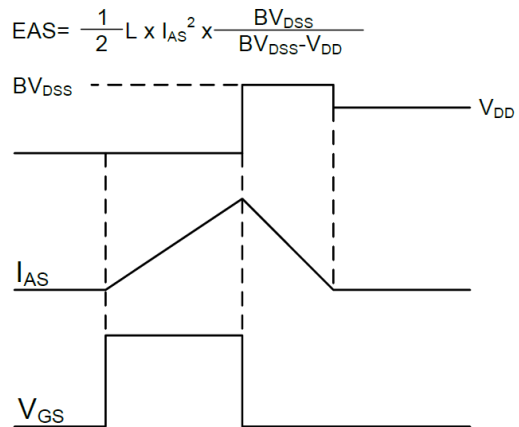
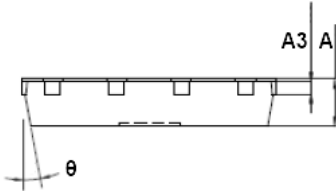
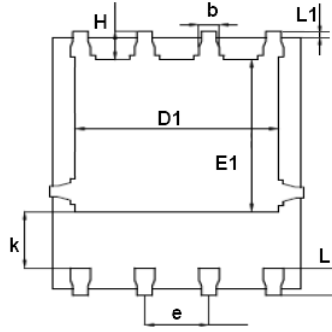
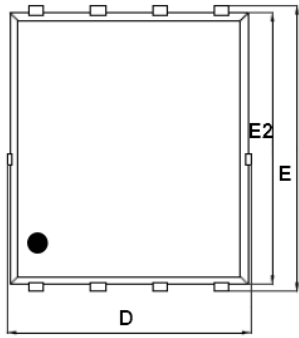


Figure 11. Unclamped Inductive Switching Waveform

## Mechanical Dimensions for PDFN5060-8L

## COMMON DIMENSIONS

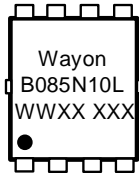


SYMBOL	MM	
	MIN	MAX
A	0.90	1.17
A3	0.20	0.35
D	4.80	5.40
E	5.90	6.15
D1	3.61	4.31
E1	3.3	3.78
E2	5.65	5.85
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.61
θ	0°	12°

## Ordering Information

Part	Package	Marking	Packing method
WMB085N10LG2	PDFN5060-8L	B085N10L	Tape and Reel

## Marking Information



B085N10L = Device code

WWXX XXX= Date code


## Contact Information

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